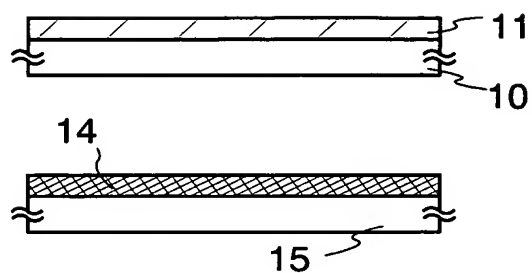


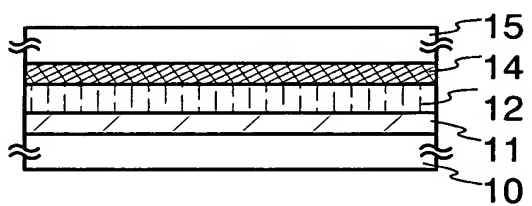


FIG. 1

(A)



(B) A state of the second substrate 15 after the adhesion



(C) Dissolution and removal processes of the second substrate 15

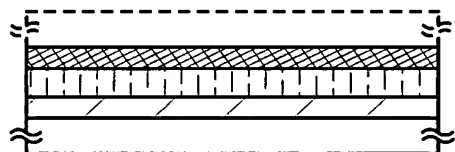
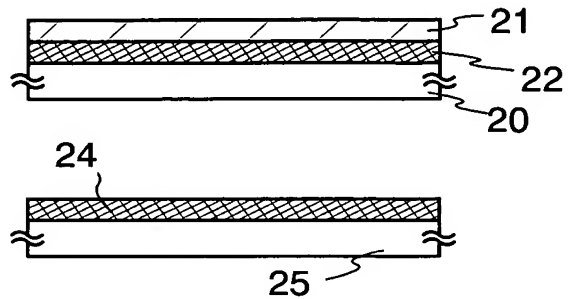
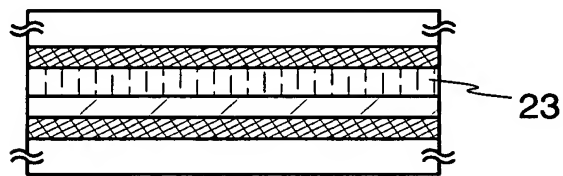


FIG. 2

(A) After forming a layer to be peeled



(B) A state of the second substrate 25 after the adhesion



(C) Dissolution and removal processes of the second substrate 25

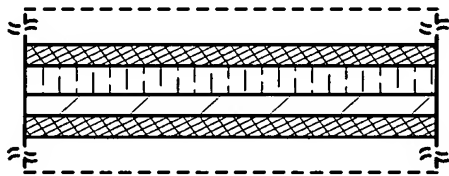
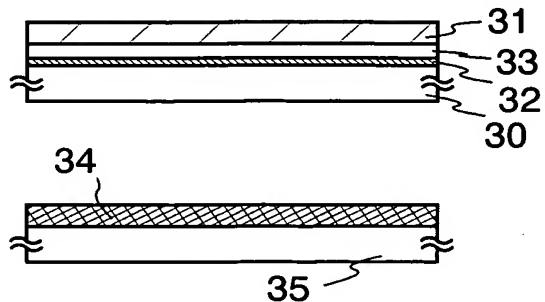
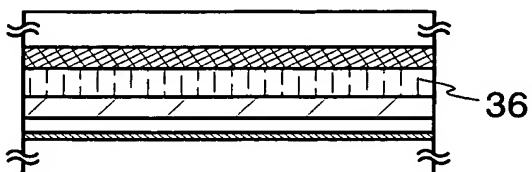


FIG. 3

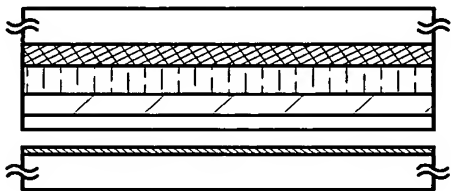
(A) After forming a layer including an element



(B) A state of the second substrate 35 after the adhesion



(C) A state of the first substrate 30 after peeling



(D) Dissolution and removal processes of the second substrate 35

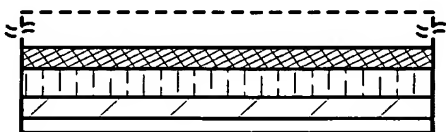
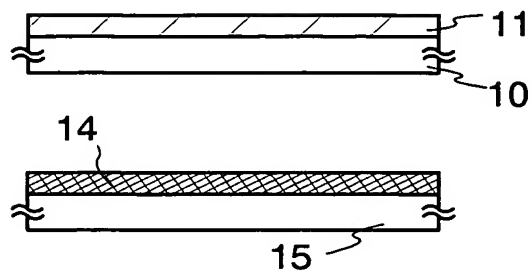
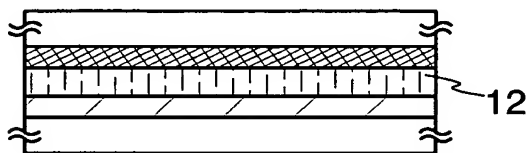


FIG. 4

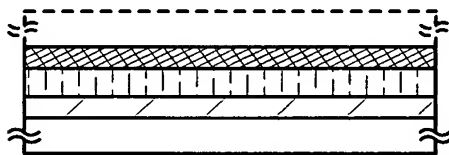
(A) After forming a layer to be peeled



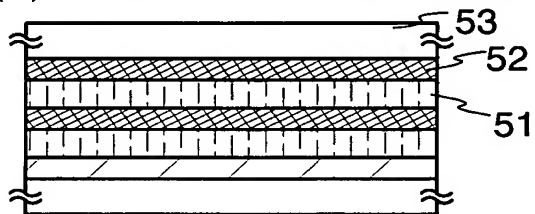
(B) A state of the second substrate 15 after the adhesion



(C) Dissolution and removal processes of the second substrate 15



(D) A state of a third substrate after the adhesion



Dissolution and removal processes of the third substrate 53

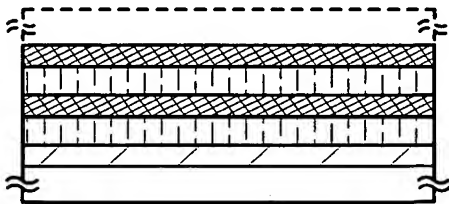
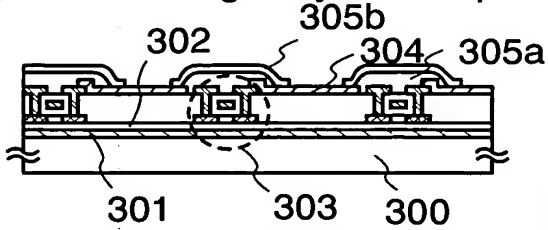
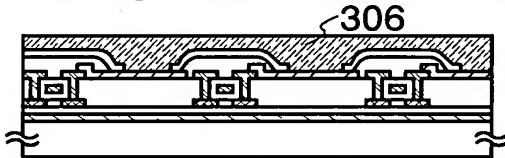


FIG. 5

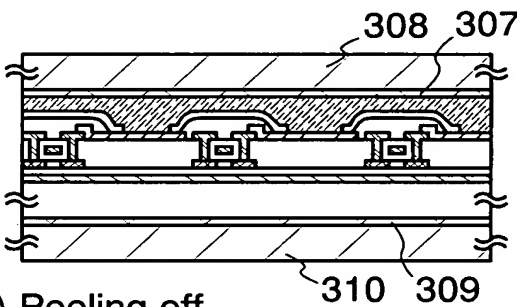
(A) After forming a layer to be peeled



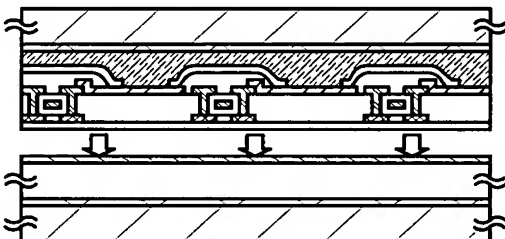
(B) Coating of water soluble resin



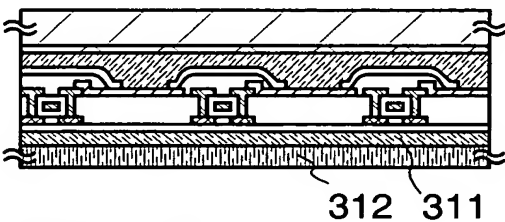
(C) Bonding with a double-stick tape



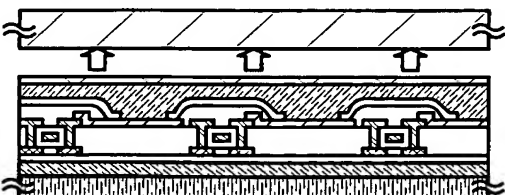
(D) Peeling-off



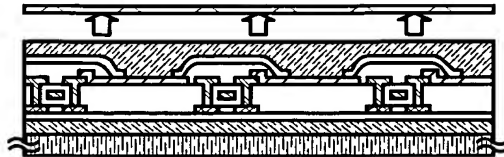
(E) Bonding of a plastic substrate



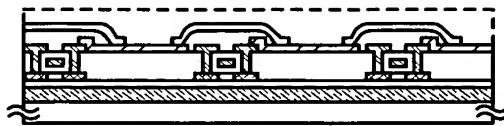
(F) Peeling-off



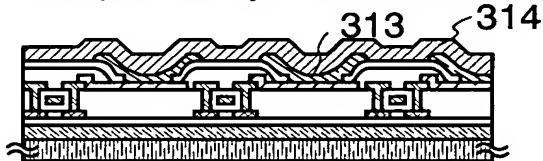
(G) Peeling-off



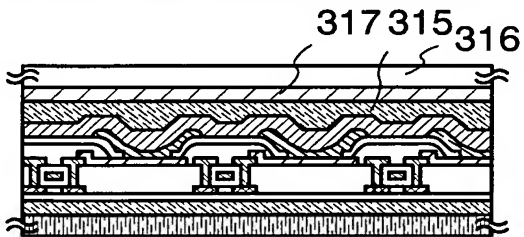
(H) Removal of water soluble resin



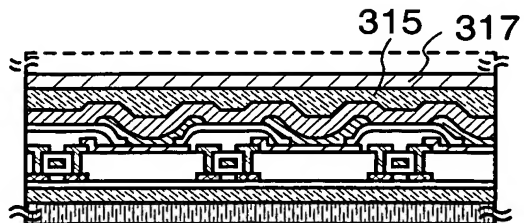
(I) Formation of an organic compound layer and a cathode



(J) Bonding a glass substrate



(K) Etching of a glass substrate



(L)

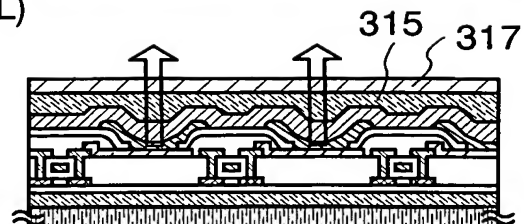
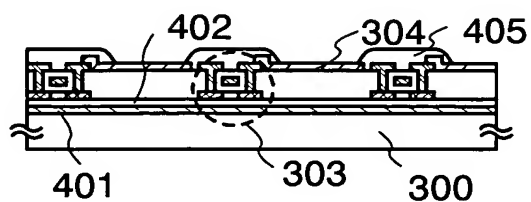
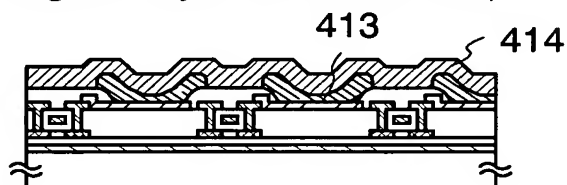


FIG. 6

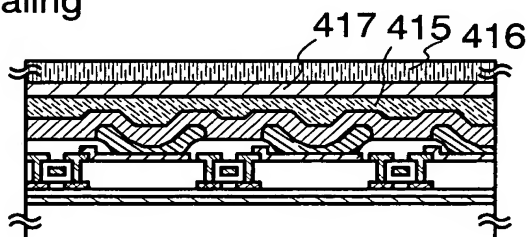
(A) A formation of a layer to be peeled (TFT)



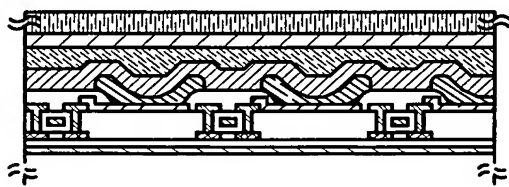
(B) A formation of a layer to be peeled (an organic layer and a cathode)



(C) Sealing



(D) Etching of a glass substrate



(E)

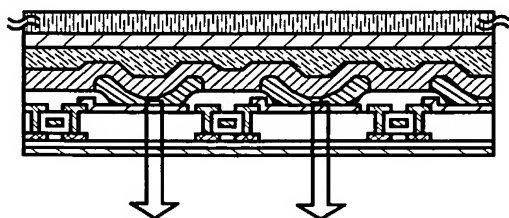
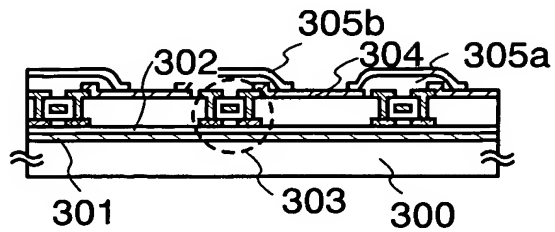
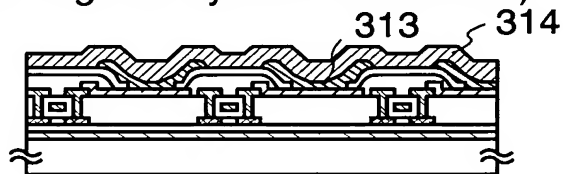


FIG. 7

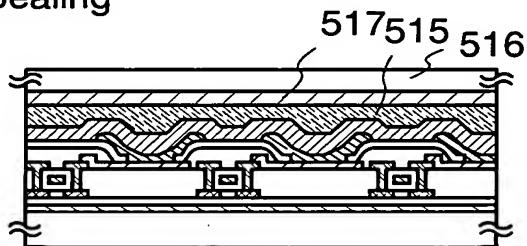
(A) A formation of a layer to be peeled (TFT)



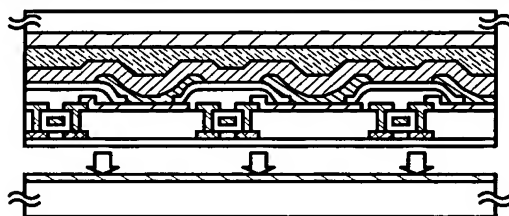
(B) A Formation of a layer to be peeled
(an organic layer and a cathode)



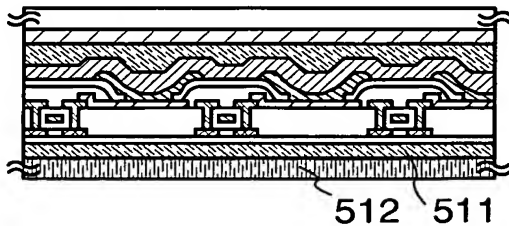
(C) Sealing



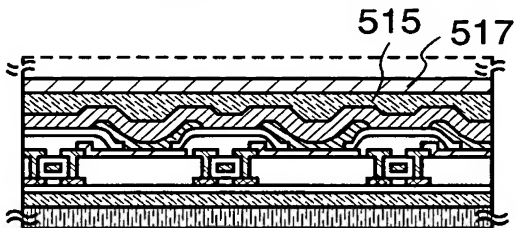
(D) Separating of a glass substrate



(E) Bonding of a plastic substrate



(F) Etching of a quartz substrate



(G)

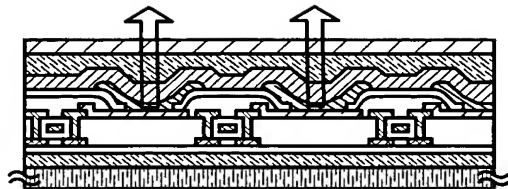


FIG. 8

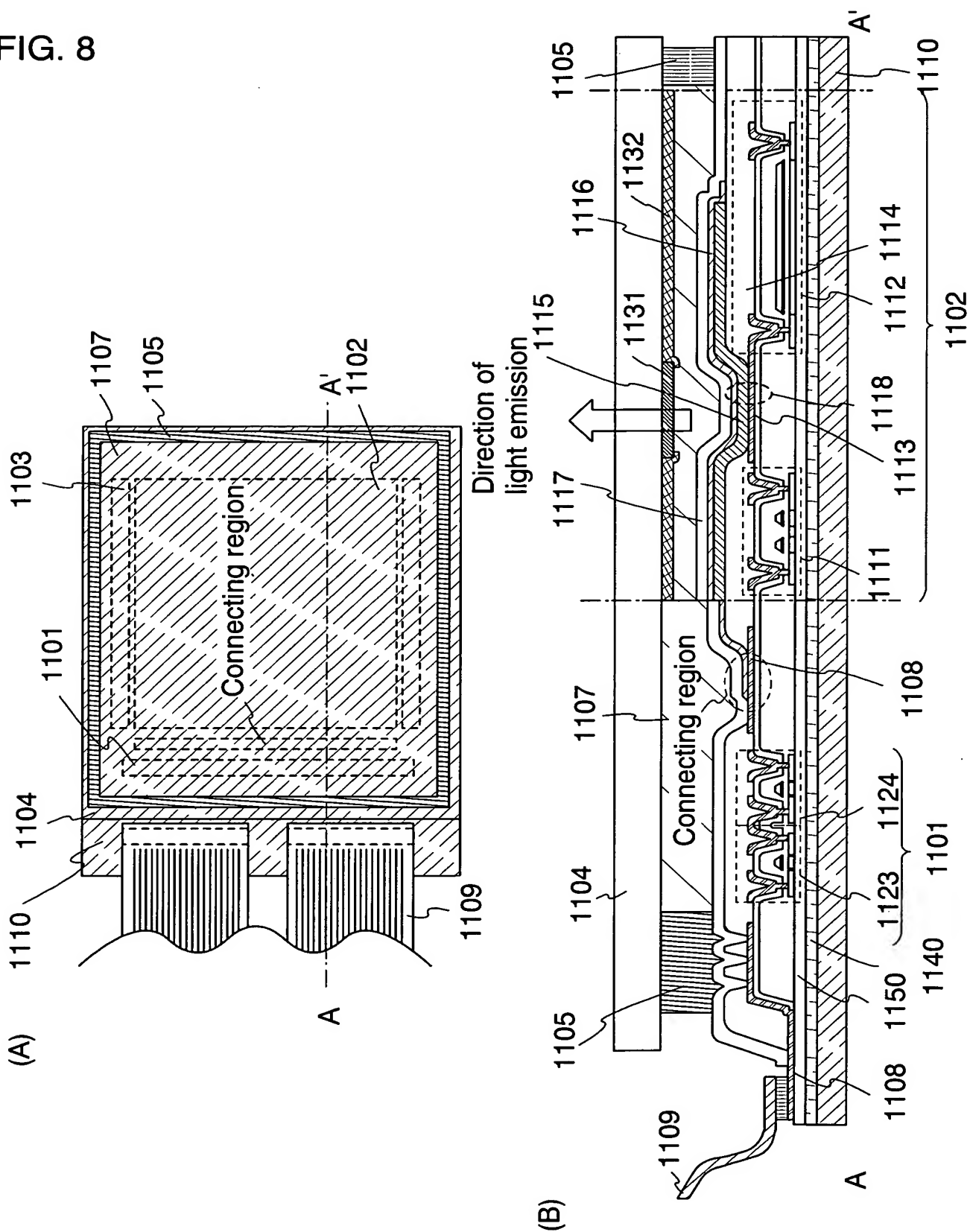


FIG. 9

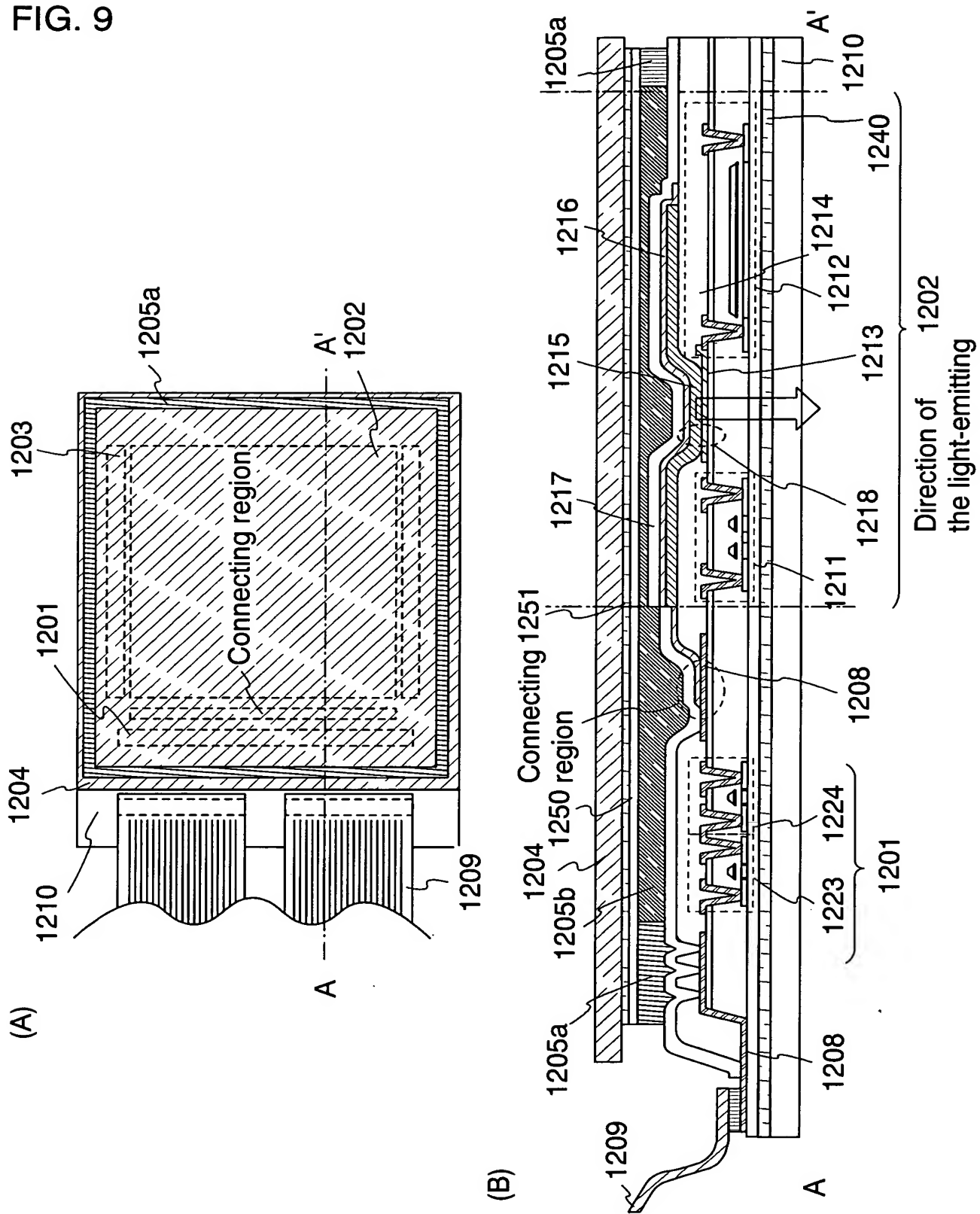


FIG. 10

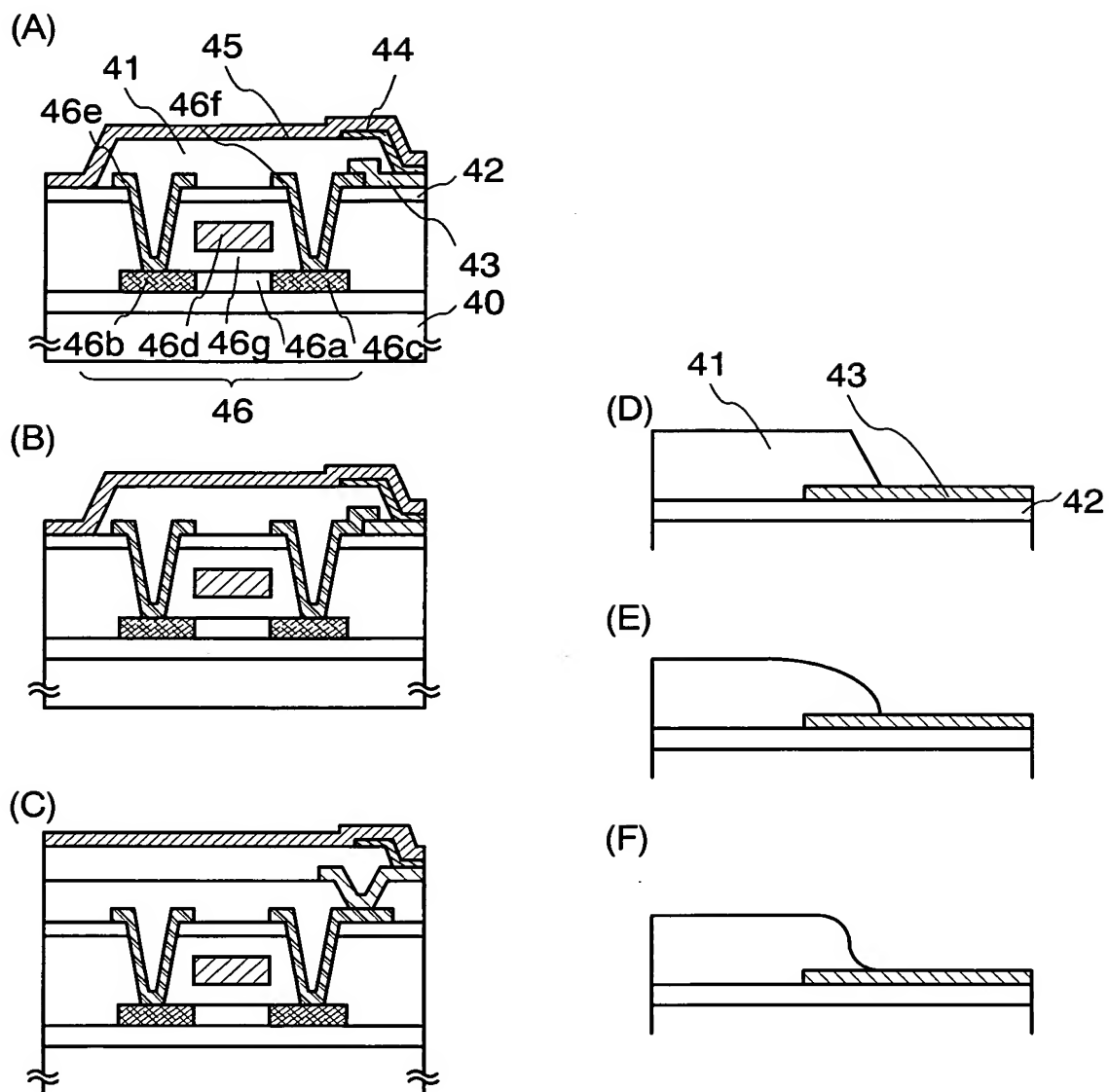
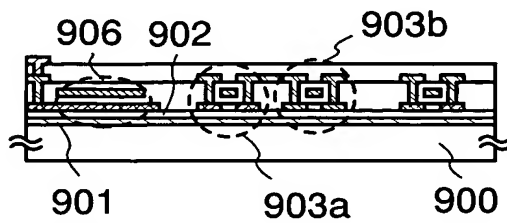
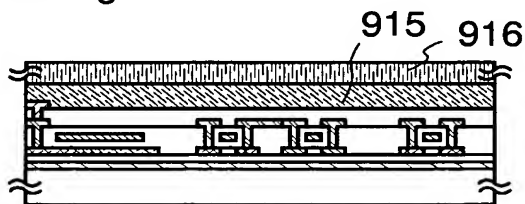


FIG. 11

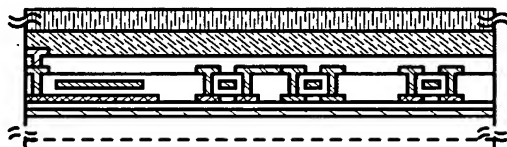
(A) A configuration of a layer to be peeled
(CPU including CMOS circuit)



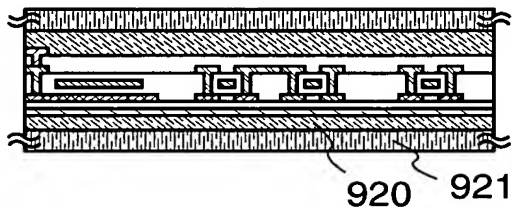
(B) Sealing



(C) Etching of a glass substrate



(D) Bonding



(E) Peeling-off

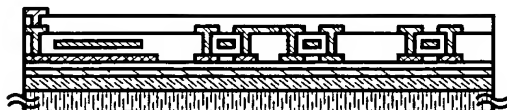


FIG. 12

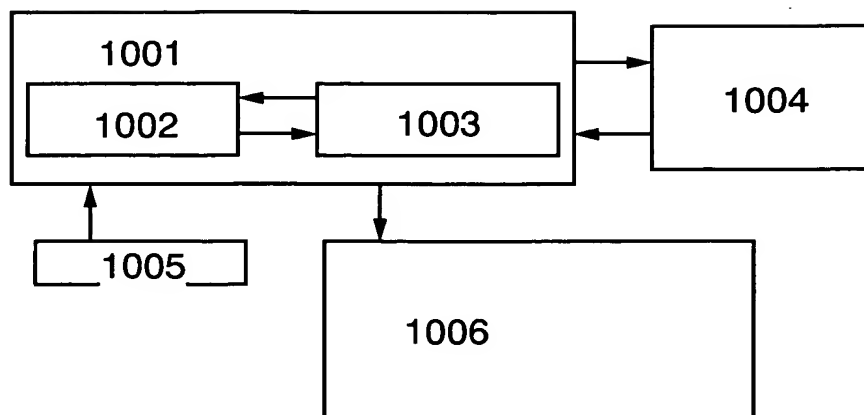


FIG. 13

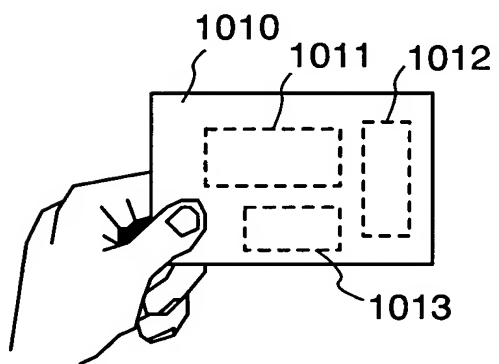


FIG. 14

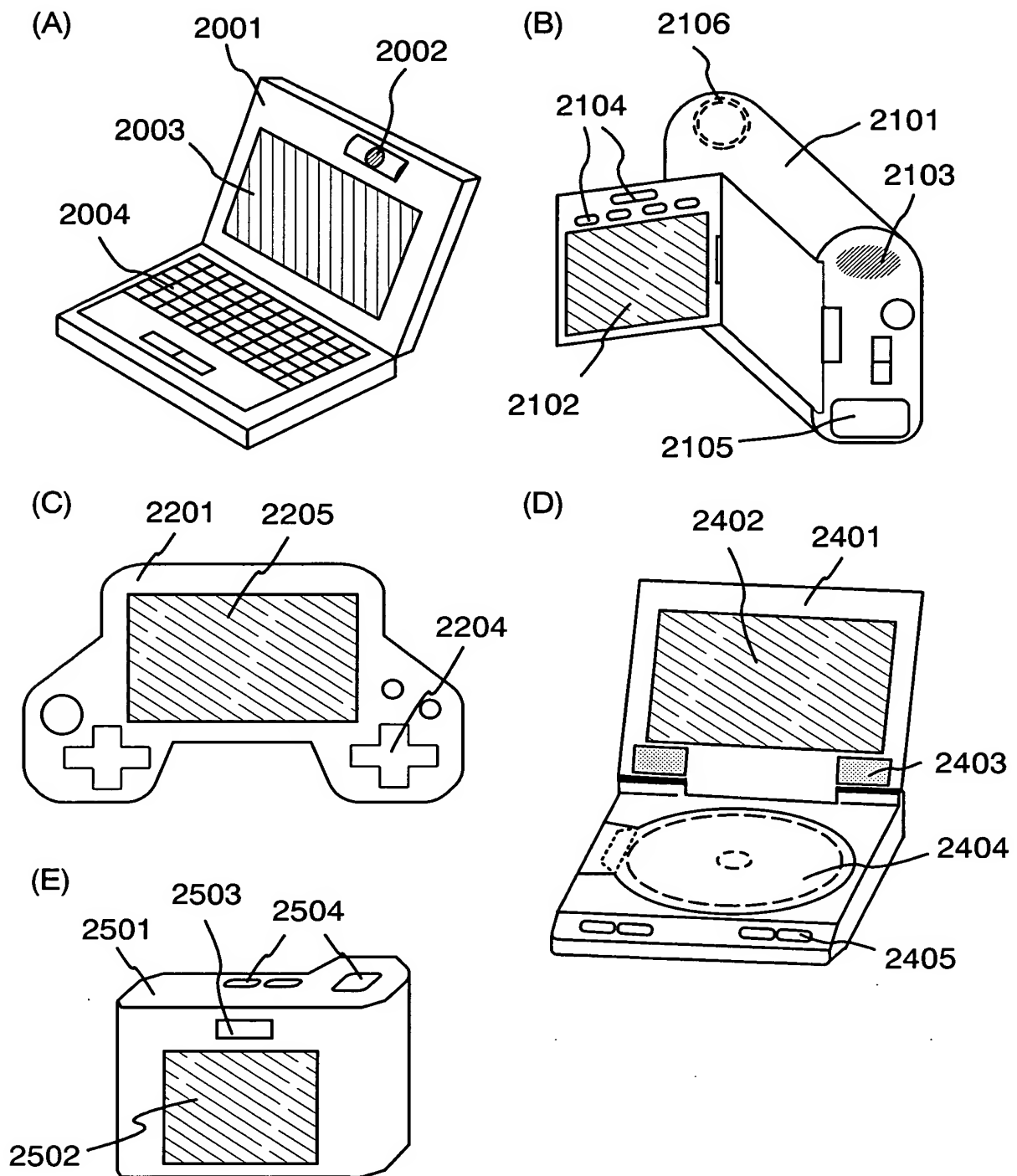
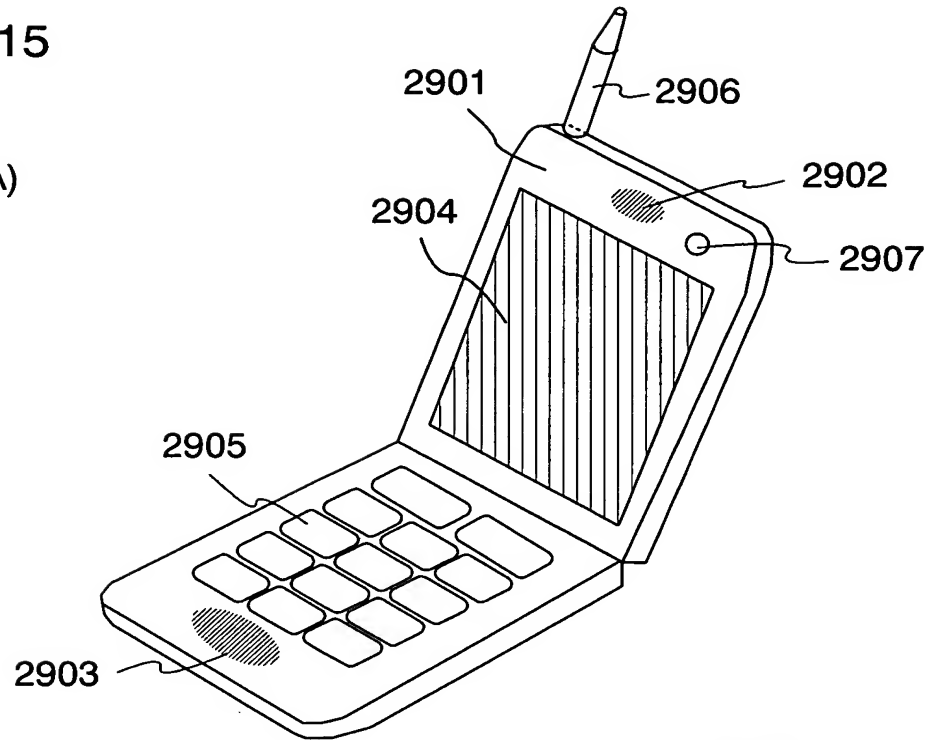
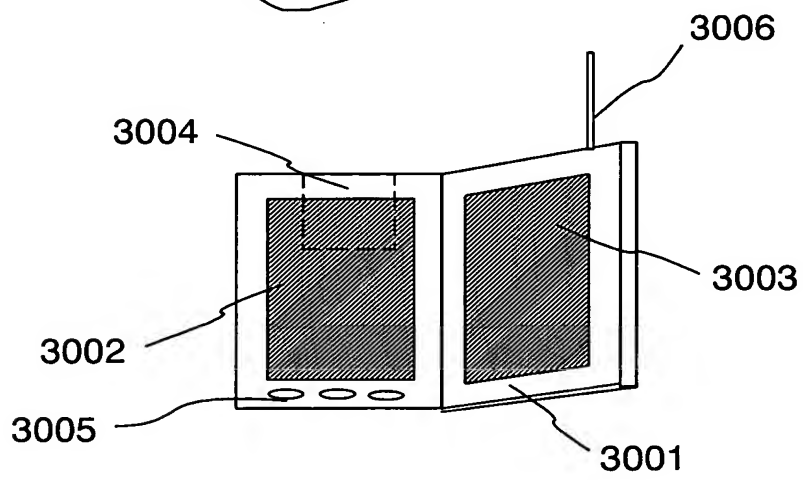


FIG. 15

(A)



(B)



(C)

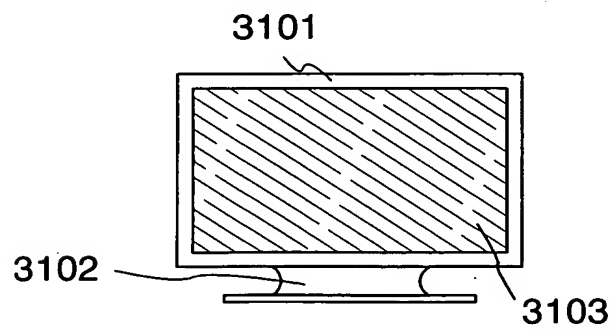
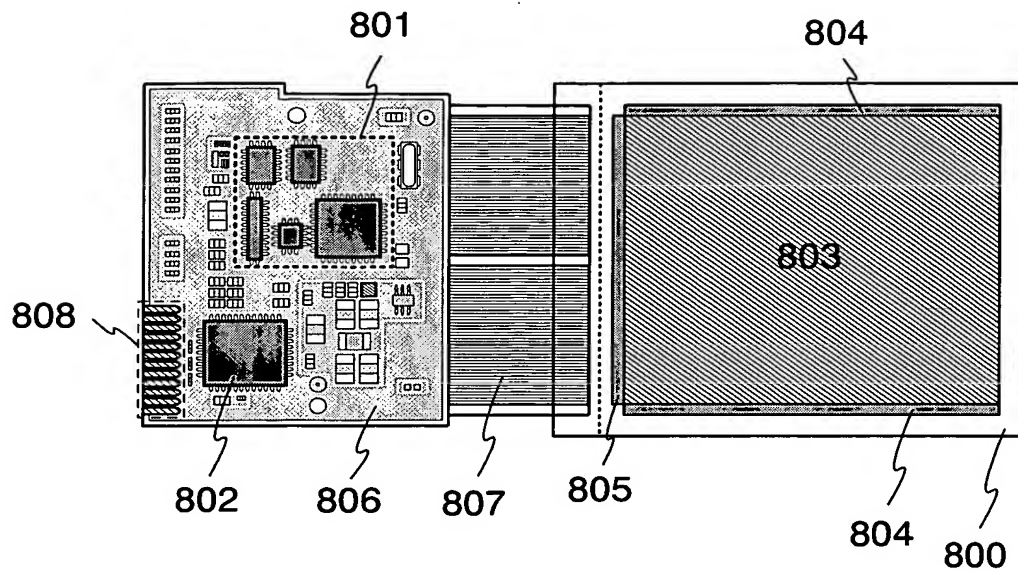


FIG. 16

(A)



(B)

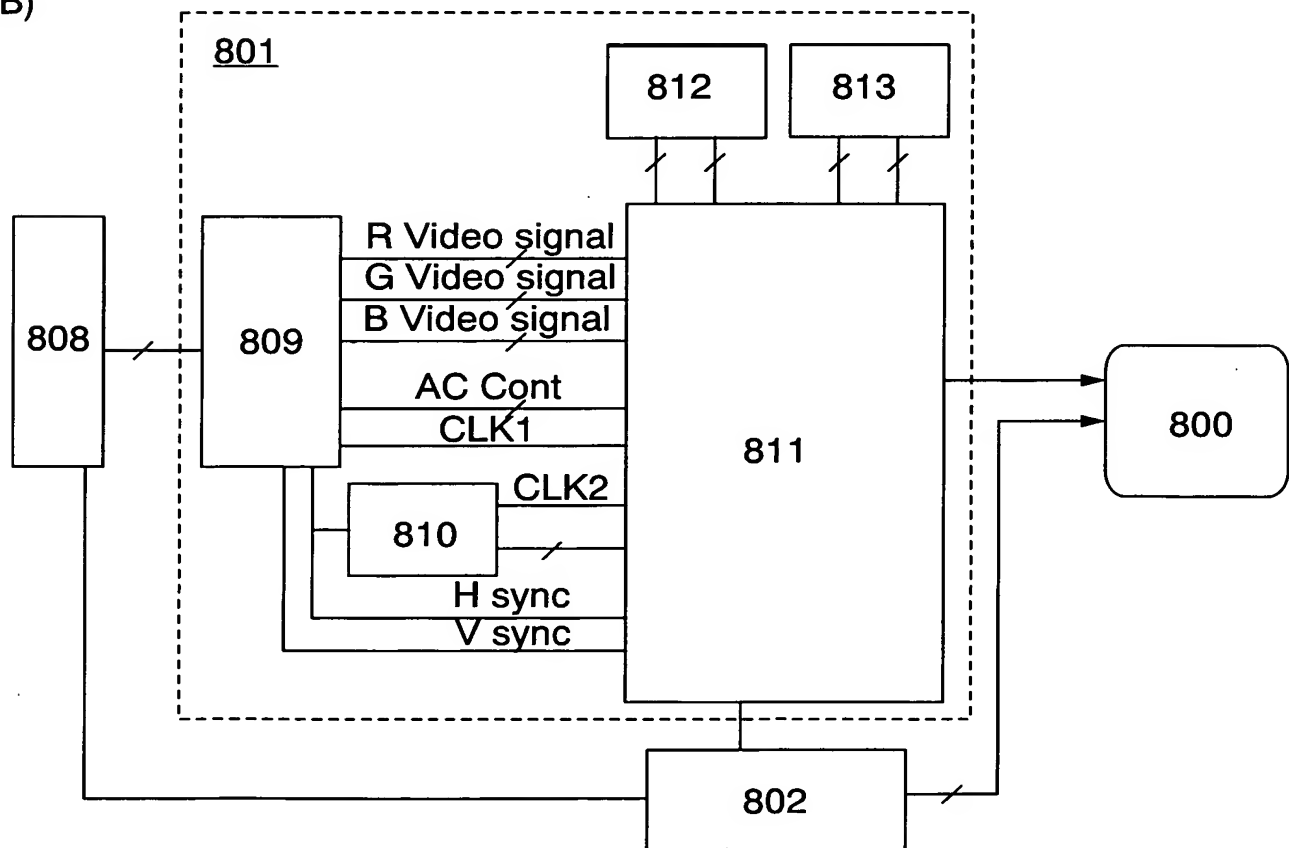


FIG. 17

